

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

PUBLICATION NUMBER : 02010606  
PUBLICATION DATE : 16-01-90

APPLICATION DATE : 28-06-88  
APPLICATION NUMBER : 63160423

APPLICANT : TDK CORP;

INVENTOR : NOMURA TAKESHI;

INT.CL. : H01B 1/22 C09D 5/24 H01F 17/00 H01G 4/40

TITLE : CONDUCTING PASTE AND THIN FILM COMPONENT USING SAME

ABSTRACT : PURPOSE: To prevent the structural defect of a conductor layer such as delamination or cracks and obtain the good characteristic with no open circuit failure or the like by containing Ag and at least one or more kinds of specific metallo-organics or their decomposed materials.

CONSTITUTION: Conducting paste is laminated on an oxide element material and concurrently burnt. A conducting material Ag and at least one or more kinds of Mg, Ti, Sn, Ca metallo-organics or their decomposed materials are contained. The metallo-organics or their decomposed materials 0.1~7wt.% in metal conversion, preferably 0.5~3wt.%, are contained against Ag. Silver oxide may be used for part Ag serving as a conducting material, or Ag-Cu, Ag-Pd alloy may be used if it is mainly made of Ag. Ag 95wt.% or above is contained in this case. In the metallo-organics, the center metal such as Mg, Ti, Sn, Ca is connected to the ligand (coordinating atom) via the hetero metal, and O, S, N is preferable for the hetero atom.

COPYRIGHT: (C)1990,JPO&Japio